

Title (en)

APPARATUS AND METHOD FOR DRILLING MICROVIA HOLES IN ELECTRICAL CIRCUIT INTERCONNECTION PACKAGES

Title (de)

VORRICHTUNG UND VERFAHREN ZUR PERFORIERUNG VON MIKROVIA-LÖCHERN IN VERPACKUNGEN VON ELEKTRISCHEN VERBINDUNGSSTELLEN VON ELEKTRISCHEN SCHALTUNGEN

Title (fr)

DISPOSITIF PERMETTANT DE FORER DES TROUS D'INTERCONNEXION MICROSCOPIQUES DANS DES BLOCS DE CONNEXION DE CIRCUIT ELECTRIQUE ET TECHNIQUE AFFERENTE

Publication

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Application

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Priority

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Abstract (en)

[origin: GB2337720A] This invention applies the use of shaped beams of laser radiation for increasing the maximum speed of tools used to laser drill microvia holes in PCB's, PWB's and other electrical circuit packages (8). With an annular spatial intensity distribution, the maximum speed can be increased several fold from machines which do not incorporate such laser beam shaping. Different hole diameters on a one device can be programmed using a set of ring beam shaping elements incorporated into a single transmissive mask element whose lateral position when placed in the beam is computer-controlled.

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H05K 3/00; **B23K 26/06**; **B23K 26/00**

IPC 8 full level

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